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Embedded - Microcontrollers - Application Specific represents a category of microcontrollers designed with unique features and capabilities tailored to specific application needs. Unlike general-purpose microcontrollers, application-specific microcontrollers are optimized for particular tasks, offering enhanced performance, efficiency, and functionality to meet the demands of specialized applications.

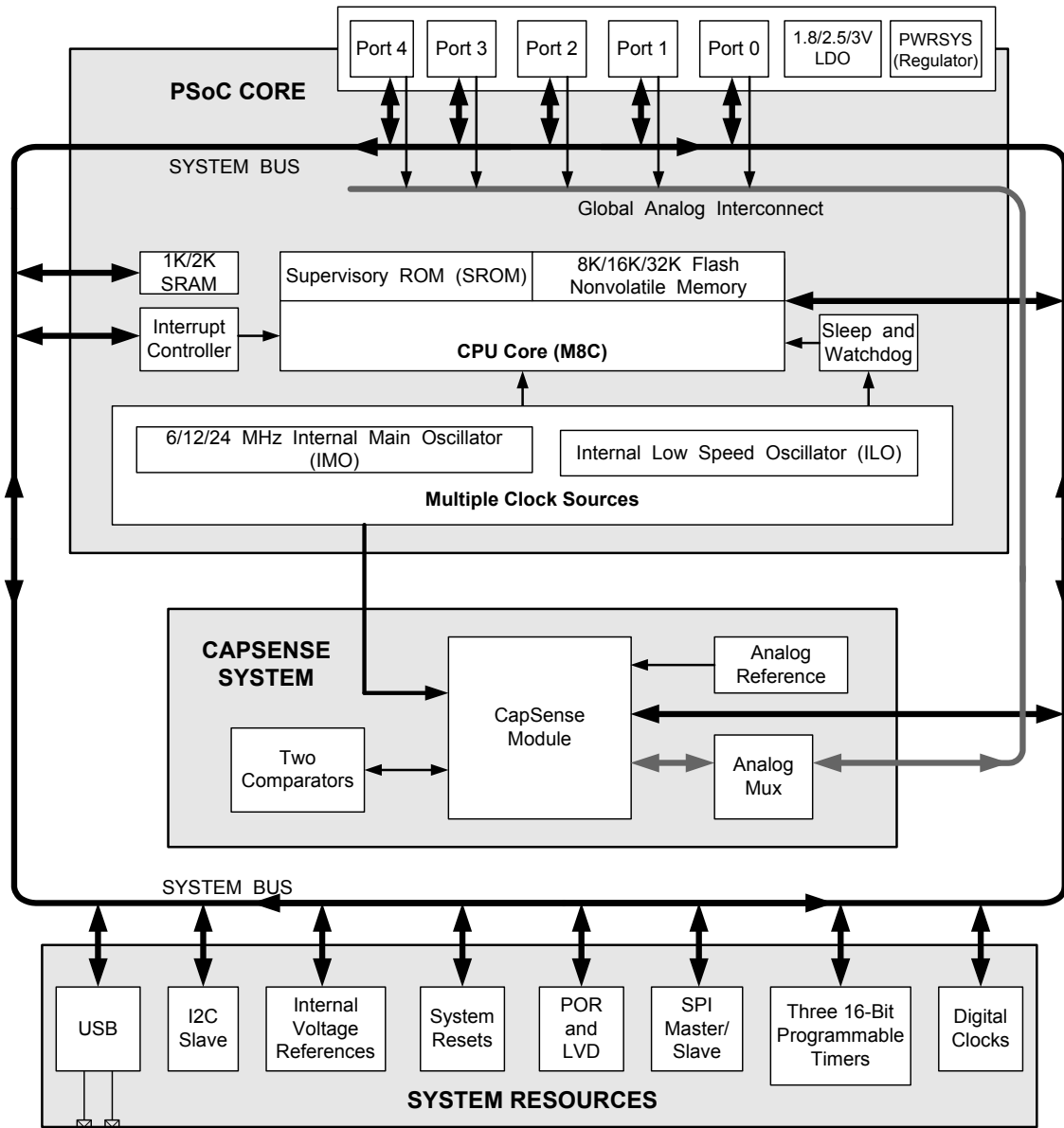
What Are Embedded - Microcontrollers - Application Specific?

Application specific microcontrollers are engineered to

Details

Product Status	Obsolete
Applications	Capacitive Sensing
Core Processor	M8C
Program Memory Type	FLASH (32kB)
Controller Series	CY8C20xx6A
RAM Size	2K x 8
Interface	I ² C, SPI, USB
Number of I/O	36
Voltage - Supply	1.71V ~ 5.5V
Operating Temperature	-40°C ~ 85°C
Mounting Type	Surface Mount
Package / Case	48-VFQFN Exposed Pad
Supplier Device Package	48-QFN (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/cy8c20066-24ltxi

Logic Block Diagram



Additional System Resources

System Resources, some of which are listed in the previous sections, provide additional capability useful to complete systems. Additional resources include low voltage detection and power on reset. The merits of each system resource are listed here:

- The I2C slave/SPI master-slave module provides 50/100/400 kHz communication over two wires. SPI communication over three or four wires runs at speeds of 46.9 kHz to 3 MHz (lower for a slower system clock).
- The I2C hardware address recognition feature reduces the already low power consumption by eliminating the need for CPU intervention until a packet addressed to the target device is received.
- Low Voltage Detection (LVD) interrupts can signal the application of falling voltage levels, while the advanced POR (Power-On-Reset) circuit eliminates the need for a system supervisor.
- An internal reference provides an absolute reference for capacitive sensing.
- A register-controlled bypass mode allows the user to disable the LDO.
- Standard Cypress PSoC IDE tools are available for debugging the CY8C20x36/46/66/96 family of parts. However, the additional trace length and a minimal ground plane in the Flex-Pod can create noise problems that make it difficult to debug the design. A custom bonded On-Chip Debug (OCD) device is available in an 48-pin QFN package. The OCD device is recommended for debugging designs that have high current and/or high analog accuracy requirements. The QFN package is compact and is connected to the ICE through a high density connector.

Getting Started

The quickest way to understand PSoC silicon is to read this data sheet and then use the PSoC Designer Integrated Development Environment (IDE). This data sheet is an overview of the PSoC integrated circuit and presents specific pin, register, and electrical specifications.

For in depth information, along with detailed programming details, see the PSoC® Programmable System-on-Chip™ Technical Reference Manual for CY8C20x36/46/66/96 PSoC Devices.

For up-to-date ordering, packaging, and electrical specification information, see the latest PSoC device data sheets on the web at www.cypress.com/psoc.

Application Notes

Application notes are an excellent introduction to the wide variety of possible PSoC designs. They are located here: www.cypress.com/psoc. Select Application Notes under the Documentation tab.

Development Kits

PSoC Development Kits are available online from Cypress at www.cypress.com/shop and through a growing number of regional and global distributors, which include Arrow, Avnet, Digi-Key, Farnell, Future Electronics, and Newark.

Training

Free PSoC technical training (on demand, webinars, and workshops) is available online at www.cypress.com/training. The training covers a wide variety of topics and skill levels to assist you in your designs.

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Development Tools

PSoC Designer is a Microsoft® Windows-based, integrated development environment for the Programmable System-on-Chip (PSoC) devices. The PSoC Designer IDE and application runs on Windows XP and Windows Vista.

This system provides design database management by project, an integrated debugger with In-Circuit Emulator, in-system programming support, and built-in support for third-party assemblers and C compilers.

PSoC Designer also supports C language compilers developed specifically for the devices in the PSoC family.

PSoC Designer Software Subsystems

System-Level View

The system-level view is a drag-and-drop visual embedded system design environment based on PSoC Express. In this view you solve design problems the same way you might think about the system. Select input and output devices based upon system requirements. Add a communication interface and define the interface to the system (registers). Define when and how an output device changes state based upon any/all other system devices. Based upon the design, PSoC Designer automatically selects one or more PSoC devices that match your system requirements.

PSoC Designer generates all embedded code, then compiles and links it into a programming file for a specific PSoC device.

Chip-Level View

The chip-level view is a more traditional integrated development environment (IDE) based on PSoC Designer 4.x. You choose a base device to work with and then select different onboard analog and digital components called user modules that use the PSoC blocks. Examples of user modules are ADCs, DACs, Amplifiers, and Filters. You configure the user modules for your chosen application and connect them to each other and to the proper pins. Then you generate your project. This prepopulates your project with APIs and libraries that you can use to program your application.

The tool also supports easy development of multiple configurations and dynamic reconfiguration. Dynamic reconfiguration allows for changing configurations at run time.

Hybrid Designs

You can begin in the system-level view, allow it to choose and configure your user modules, routing, and generate code, then switch to the chip-level view to gain complete control over on-chip resources. All views of the project share common code editor, builder, and common debug, emulation, and programming tools.

Code Generation Tools

PSoC Designer supports multiple third-party C compilers and assemblers. The code generation tools work seamlessly within the PSoC Designer interface and have been tested with a full range of debugging tools. The choice is yours.

Assemblers. The assemblers allow assembly code to be merged seamlessly with C code. Link libraries automatically use absolute addressing or are compiled in relative mode, and linked with other software modules to get absolute addressing.

C Language Compilers. C language compilers are available that support the PSoC family of devices. The products allow you to create complete C programs for the PSoC family devices.

The optimizing C compilers provide all the features of C tailored to the PSoC architecture. They come complete with embedded libraries providing port and bus operations, standard keypad and display support, and extended math functionality.

Debugger

PSoC Designer has a debug environment that provides hardware in-circuit emulation, allowing you to test the program in a physical system while providing an internal view of the PSoC device. Debugger commands allow the designer to read and program and read and write data memory, read and write I/O registers, read and write CPU registers, set and clear breakpoints, and provide program run, halt, and step control. The debugger also allows the designer to create a trace buffer of registers and memory locations of interest.

Online Help System

The online help system displays online, context-sensitive help for the user. Designed for procedural and quick reference, each functional subsystem has its own context-sensitive help. This system also provides tutorials and links to FAQs and an Online Support Forum to aid the designer in getting started.

In-Circuit Emulator

A low cost, high functionality In-Circuit Emulator (ICE) is available for development support. This hardware has the capability to program single devices.

The emulator consists of a base unit that connects to the PC by way of a USB port. The base unit is universal and operates with all PSoC devices. Emulation pods for each device family are available separately. The emulation pod takes the place of the PSoC device in the target board and performs full speed (24 MHz) operation.

Designing with PSoC Designer

The development process for the PSoC device differs from that of a traditional fixed function microprocessor. The configurable analog and digital hardware blocks give the PSoC architecture a unique flexibility that pays dividends in managing specification change during development and by lowering inventory costs. These configurable resources, called PSoC Blocks, have the ability to implement a wide variety of user-selectable functions.

The PSoC development process can be summarized in the following four steps:

1. Select Components
2. Configure Components
3. Organize and Connect
4. Generate, Verify, and Debug

Select Components

Both the system-level and chip-level views provide a library of pre-built, pre-tested hardware peripheral components. In the system-level view these components are called “drivers” and correspond to inputs (a thermistor, for example), outputs (a brushless DC fan, for example), communication interfaces (I²C-bus, for example), and the logic to control how they interact with one another (called valuator).

In the chip-level view the components are called “user modules.” User modules make selecting and implementing peripheral devices simple, and come in analog, digital, and programmable system-on-chip varieties.

Configure Components

Each of the components you select establishes the basic register settings that implement the selected function. They also provide parameters and properties that allow you to tailor their precise configuration to your particular application. For example, a Pulse Width Modulator (PWM) User Module configures one or more digital PSoC blocks, one for each 8 bits of resolution. The user module parameters permit you to establish the pulse width and duty cycle. Configure the parameters and properties to correspond to your chosen application. Enter values directly or by selecting values from drop-down menus.

Both the system-level drivers and chip-level user modules are documented in data sheets that are viewed directly in PSoC Designer. These data sheets explain the internal operation of the component and provide performance specifications. Each data sheet describes the use of each user module parameter or driver property, and other information you may need to successfully implement your design.

Organize and Connect

You build signal chains at the chip level by interconnecting user modules to each other and the I/O pins, or connect system-level inputs, outputs, and communication interfaces to each other with valuator functions.

In the system-level view selecting a potentiometer driver to control a variable speed fan driver and setting up the valuator to control the fan speed based on input from the pot selects, places, routes, and configures a programmable gain amplifier (PGA) to buffer the input from the potentiometer, an analog-to-digital converter (ADC) to convert the potentiometer's output to a digital signal, and a PWM to control the fan.

In the chip-level view, you perform the selection, configuration, and routing so that you have complete control over the use of all on-chip resources.

Generate, Verify, and Debug

When you are ready to test the hardware configuration or move on to developing code for the project, you perform the “Generate Configuration Files” step. This causes PSoC Designer to generate source code that automatically configures the device to your specification and provides the software for the system.

Both system-level and chip-level designs generate software based on your design. The chip-level design provides application programming interfaces (APIs) with high-level functions to control and respond to hardware events at run time and interrupt service routines that you can adapt as needed. The system-level design also generates a C main() program that completely controls the chosen application and contains placeholders for custom code at strategic positions allowing you to further refine the software without disrupting the generated code.

A complete code development environment allows you to develop and customize your applications in C, assembly language, or both.

The last step in the development process takes place inside PSoC Designer's Debugger (access by clicking the Connect icon). PSoC Designer downloads the HEX image to the ICE where it runs at full speed. PSoC Designer debugging capabilities rival those of systems costing many times more. In addition to traditional single-step, run-to-breakpoint and watch-variable features, the debug interface provides a large trace buffer and allows you to define complex breakpoint events that include monitoring address and data bus values, memory locations and external signals.

Pinouts

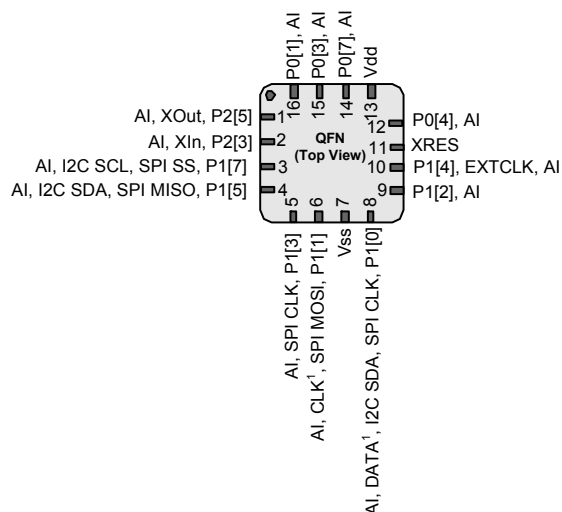
The CY8C20x36/46/66/96 PSoC device is available in a variety of packages which are listed and illustrated in the following tables. Every port pin (labeled with a “P”) is capable of Digital I/O and connection to the common analog bus. However, Vss, Vdd, and XRES are not capable of Digital I/O.

16-Pin QFN (No E-Pad)

Table 2. Pin Definitions - CY8C20236, CY8C20246 PSoC Device ^[2]

Pin No.	Type		Name	Description
	Digital	Analog		
1	I/O	I	P2[5]	Crystal output (XOut)
2	I/O	I	P2[3]	Crystal input (XIn)
3	IOHR	I	P1[7]	I2C SCL, SPI SS
4	IOHR	I	P1[5]	I2C SDA, SPI MISO
5	IOHR	I	P1[3]	SPI CLK
6	IOHR	I	P1[1]	ISSP CLK ^[1] , I2C SCL, SPI MOSI
7	Power		Vss	Ground connection
8	IOHR	I	P1[0]	ISSP DATA ^[1] , I2C SDA, SPI CLK
9	IOHR	I	P1[2]	
10	IOHR	I	P1[4]	Optional external clock (EXTCLK)
11	Input		XRES	Active high external reset with internal pull down
12	IOH	I	P0[4]	
13	Power		Vdd	Supply voltage
14	IOH	I	P0[7]	
15	IOH	I	P0[3]	Integrating input
16	IOH	I	P0[1]	Integrating input

Figure 2. CY8C20236, CY8C20246 PSoC Device



LEGEND A = Analog, I = Input, O = Output, OH = 5 mA High Output Drive, R = Regulated Output.

Notes

- These are the ISSP pins, which are not High Z at POR (Power On Reset).
- During power up or reset event, device P1[1] and P1[0] may disturb the I2C bus. Use alternate pins if you encounter any issues.

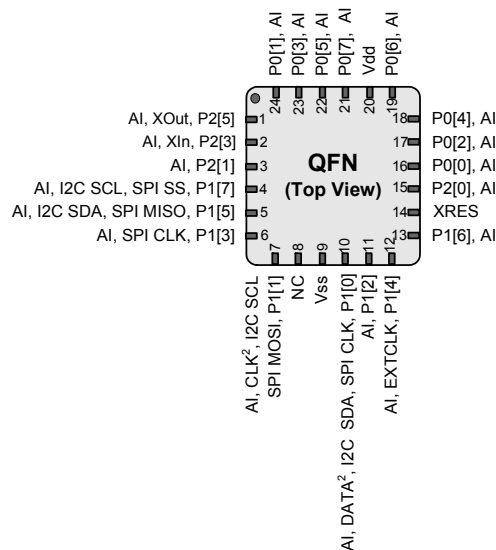
24-Pin QFN

Table 3. Pin Definitions - CY8C20336, CY8C20346 [2, 3]

Pin No.	Type		Name	Description
	Digital	Analog		
1	I/O	I	P2[5]	Crystal output (XOut)
2	I/O	I	P2[3]	Crystal input (XIn)
3	I/O	I	P2[1]	
4	IOHR	I	P1[7]	I2C SCL, SPI SS
5	IOHR	I	P1[5]	I2C SDA, SPI MISO
6	IOHR	I	P1[3]	SPI CLK
7	IOHR	I	P1[1]	ISSP CLK ^[1] , I2C SCL, SPI MOSI
8			NC	No connection
9	Power		Vss	Ground connection
10	IOHR	I	P1[0]	ISSP DATA ^[1] , I2C SDA, SPI CLK
11	IOHR	I	P1[2]	
12	IOHR	I	P1[4]	Optional external clock input (EXTCLK)
13	IOHR	I	P1[6]	
14	Input		XRES	Active high external reset with internal pull down
15	I/O	I	P2[0]	
16	IOH	I	P0[0]	
17	IOH	I	P0[2]	
18	IOH	I	P0[4]	
19	IOH	I	P0[6]	
20	Power		Vdd	Supply voltage
21	IOH	I	P0[7]	
22	IOH	I	P0[5]	
23	IOH	I	P0[3]	Integrating input
24	IOH	I	P0[1]	Integrating input
CP	Power		Vss	Center pad must be connected to ground

LEGEND A = Analog, I = Input, O = Output, OH = 5 mA High Output Drive, R = Regulated Output.

Figure 3. CY8C20336, CY8C20346 PSoC Device



Note

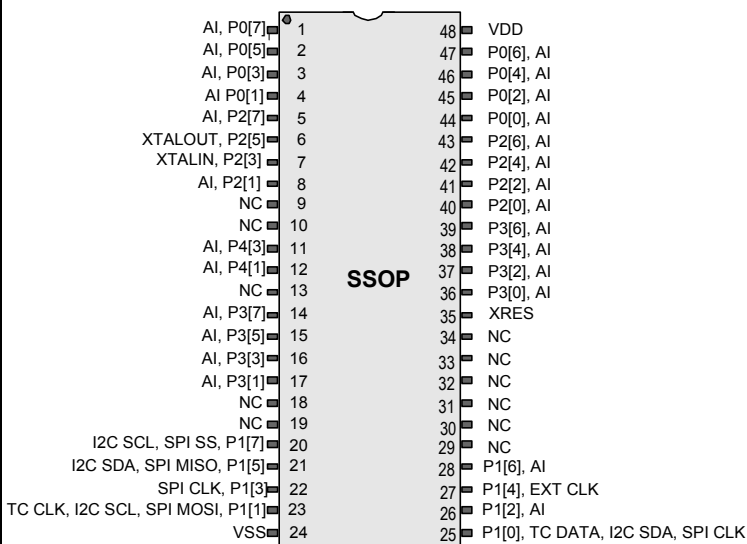
- The center pad (CP) on the QFN package must be connected to ground (Vss) for best mechanical, thermal, and electrical performance. If not connected to ground, it must be electrically floated and not connected to any other signal.

48-Pin SSOP

Table 7. Pin Definitions - CY8C20536, CY8C20546, and CY8C20566 PSoC Device^[2]

Pin No.	Digital	Analog	Name	Description
1	IOH	I	P0[7]	
2	IOH	I	P0[5]	
3	IOH	I	P0[3]	
4	IOH	I	P0[1]	
5	I/O	I	P2[7]	
6	I/O	I	P2[5]	XTAL Out
7	I/O	I	P2[3]	XTAL In
8	I/O	I	P2[1]	
9			NC	No connection
10			NC	No connection
11	I/O	I	P4[3]	
12	I/O	I	P4[1]	
13			NC	No connection
14	I/O	I	P3[7]	
15	I/O	I	P3[5]	
16	I/O	I	P3[3]	
17	I/O	I	P3[1]	
18			NC	No connection
19			NC	No connection
20	IOHR	I	P1[7]	I2C SCL, SPI SS
21	IOHR	I	P1[5]	I2C SDA, SPI MISO
22	IOHR	I	P1[3]	SPI CLK
23	IOHR	I	P1[1]	TC CLK ^[1] , I2C SCL, SPI MOSI
24			VSS	Ground Pin
25	IOHR	I	P1[0]	TC DATA ^[1] , I2C SDA, SPI CLK
26	IOHR	I	P1[2]	
27	IOHR	I	P1[4]	EXT CLK
28	IOHR	I	P1[6]	
29			NC	No connection
30			NC	No connection
31			NC	No connection
32			NC	No connection
33			NC	No connection
34			NC	No connection
35			XRES	Active high external reset with internal pull down
36	I/O	I	P3[0]	
37	I/O	I	P3[2]	
38	I/O	I	P3[4]	
39	I/O	I	P3[6]	
40	I/O	I	P2[0]	

Figure 6. CY8C20536, CY8C20546, and CY8C20566 PSoC Device



Pin No.	Digital	Analog	Name	Description
41	I/O	I	P2[2]	
42	I/O	I	P2[4]	
43	I/O	I	P2[6]	
44	IOH	I	P0[0]	
45	IOH	I	P0[2]	
46	IOH	I	P0[4]	
47	IOH	I	P0[6]	
48	Power		Vdd	Power Pin

LEGEND A = Analog, I = Input, O = Output, NC = No Connection, H = 5 mA High Output Drive, R = Regulated Output Option.

Absolute Maximum Ratings

Exceeding maximum ratings may shorten the useful life of the device. User guidelines are not tested.

Table 12. Absolute Maximum Ratings

Symbol	Description	Conditions	Min	Typ	Max	Units
T _{STG}	Storage Temperature	Higher storage temperatures reduces data retention time. Recommended Storage Temperature is +25°C ± 25°C. Extended duration storage temperatures above 85°C degrades reliability.	–55	+25	+125	°C
V _{DD}	Supply Voltage Relative to V _{SS}		–0.5	–	+6.0	V
V _{IO}	DC Input Voltage		V _{SS} – 0.5	–	V _{DD} + 0.5	V
V _{IOZ}	DC Voltage Applied to Tri-state		V _{SS} – 0.5	–	V _{DD} + 0.5	V
I _{MIO}	Maximum Current into any Port Pin		–25	–	+50	mA
ESD	Electro Static Discharge Voltage	Human Body Model ESD	2000	–	–	V
LU	Latch up Current	In accordance with JESD78 standard	–	–	200	mA

Operating Temperature

Table 13. Operating Temperature

Symbol	Description	Conditions	Min	Typ	Max	Units
T _A	Ambient Temperature		–40	–	+85	°C
T _J	Operational Die Temperature	The temperature rise from ambient to junction is package specific. Refer the table Thermal Impedances per Package on page 34 . The user must limit the power consumption to comply with this requirement.	–40	–	+100	°C

Table 15. 3.0V to 5.5V DC GPIO Specifications *(continued)*

Symbol	Description	Conditions	Min	Typ	Max	Units
V_{OH10}	High Output Voltage Port 1 Pins with LDO Enabled for 1.8V Out	$I_{OH} = 1\text{ mA}$, $V_{dd} > 2.7\text{V}$, maximum of 20 mA source current in all IOs	1.20	–	–	V
V_{OL}	Low Output Voltage	$I_{OL} = 25\text{ mA}$, $V_{dd} > 3.3\text{V}$, maximum of 60 mA sink current on even port pins (for example, P0[2] and P1[4]) and 60 mA sink current on odd port pins (for example, P0[3] and P1[5])	–	–	0.75	V
V_{IL}	Input Low Voltage		–	–	0.80	V
V_{IH}	Input High Voltage		2.00	–		V
V_H	Input Hysteresis Voltage		–	80	–	mV
I_{IL}	Input Leakage (Absolute Value)		–	0.001	1	μA
C_{PIN}	Pin Capacitance	Package and pin dependent Temp = 25°C	0.5	1.7	5	pF

DC POR and LVD Specifications

The following table lists guaranteed maximum and minimum specifications for the entire voltage and temperature ranges.

Table 23. DC POR and LVD Specifications

Symbol	Description	Conditions	Min	Typ	Max	Units
V _{PPOR0}	Vdd Value for PPOR Trip PORLEV[1:0] = 00b, HPOR = 0	Vdd must be greater than or equal to 1.71V during startup, reset from the XRES pin, or reset from watchdog.	1.61	1.66	1.71	V
V _{PPOR1}	PORLEV[1:0] = 00b, HPOR = 1			2.36	2.41	V
V _{PPOR2}	PORLEV[1:0] = 01b, HPOR = 1		–	2.60	2.66	V
V _{PPOR3}	PORLEV[1:0] = 10b, HPOR = 1			2.82	2.95	V
V _{LVD0}	Vdd Value for LVD Trip VM[2:0] = 000b		2.40 ^[6]	2.45	2.51	V
V _{LVD1}	VM[2:0] = 001b		2.64 ^[7]	2.71	2.78	V
V _{LVD2}	VM[2:0] = 010b		2.85 ^[8]	2.92	2.99	V
V _{LVD3}	VM[2:0] = 011b		2.95	3.02	3.09	V
V _{LVD4}	VM[2:0] = 100b		3.06	3.13	3.20	V
V _{LVD5}	VM[2:0] = 101b		1.84	1.90	2.32	V
V _{LVD6}	VM[2:0] = 110b		1.75 ^[9]	1.80	1.84	V
V _{LVD7}	VM[2:0] = 111b		4.62	4.73	4.83	V

DC Programming Specifications

The following table lists guaranteed maximum and minimum specifications for the entire voltage and temperature ranges.

Table 24. DC Programming Specifications

Symbol	Description	Conditions	Min	Typ	Max	Units
V _{ddIWRITE}	Supply Voltage for Flash Write Operations		1.71	–	5.25	V
I _{DDP}	Supply Current During Programming or Verify		–	5	25	mA
V _{ILP}	Input Low Voltage During Programming or Verify	See the appropriate DC General Purpose IO Specifications on page 19	–	–	V _{IL}	V
V _{IHP}	Input High Voltage During Programming or Verify	See appropriate DC General Purpose IO Specifications on page 19 table on pages 15 or 16	V _{IH}	–	–	V
I _{ILP}	Input Current when Applying Vilp to P1[0] or P1[1] During Programming or Verify	Driving internal pull down resistor	–	–	0.2	mA
I _{IHP}	Input Current when Applying Vihp to P1[0] or P1[1] During Programming or Verify	Driving internal pull down resistor	–	–	1.5	mA
V _{OLP}	Output Low Voltage During Programming or Verify		–	–	V _{ss} + 0.75	V
V _{OHP}	Output High Voltage During Programming or Verify	See appropriate DC General Purpose IO Specifications on page 19 table on page 16. For Vdd > 3V use V _{OH4} in Table 13 on page 18 .	V _{OH}	–	Vdd	V
Flash _{ENPB}	Flash Write Endurance	Erase/write cycles per block	50,000	–	–	–
Flash _{DR}	Flash Data Retention	Following maximum Flash write cycles; ambient temperature of 55°C	10	20	–	Years

Notes

6. Always greater than 50 mV above V_{PPOR1} voltage for falling supply.
7. Always greater than 50 mV above V_{PPOR2} voltage for falling supply.
8. Always greater than 50 mV above V_{PPOR3} voltage for falling supply.
9. Always greater than 50 mV above V_{PPOR0} voltage for falling supply.

AC Chip-Level Specifications

The following table lists guaranteed maximum and minimum specifications for the entire voltage and temperature ranges.

Table 25. AC Chip-Level Specifications

Symbol	Description	Conditions	Min	Typ	Max	Units
F _{CPU}	CPU Frequency		5.7	–	25.2	MHz
F _{32K1}	Internal Low Speed Oscillator Frequency		19	32	50	kHz
F _{IMO24}	Internal Main Oscillator Frequency at 24 MHz Setting		22.8	24	25.2	MHz
F _{IMO12}	Internal Main Oscillator Frequency at 12 MHz Setting		11.4	12	12.6	MHz
F _{IMO6}	Internal Main Oscillator Frequency at 6 MHz Setting		5.7	6.0	6.3	MHz
DC _{IMO}	Duty Cycle of IMO		40	50	60	%
T _{RAMP}	Supply Ramp Time		20	–	–	μs
T _{XRST}	External Reset Pulse Width at Power Up	After supply voltage is valid	1			ms
T _{XRST2}	External Reset Pulse Width after Power Up ^[10]	Applies after part has booted	10			μs

Note

10. The minimum required XRES pulse length is longer when programming the device (see [Table 32 on page 28](#)).

AC General Purpose IO Specifications

The following table lists guaranteed maximum and minimum specifications for the entire voltage and temperature ranges.

Table 26. AC GPIO Specifications

Symbol	Description	Conditions	Min	Typ	Max	Units
F_{GPIO}	GPIO Operating Frequency	Normal Strong Mode Port 0, 1	0	–	6 MHz for 1.71V < Vdd < 2.4V 12 MHz for 2.4V < Vdd < 5.5V	MHz
TRise23	Rise Time, Strong Mode, Cload = 50 pF Ports 2 or 3	Vdd = 3.0 to 3.6V, 10% – 90%	15	–	80	ns
TRise23L	Rise Time, Strong Mode Low Supply, Cload = 50 pF, Ports 2 or 3	Vdd = 1.71 to 3.0V, 10% – 90%	15	–	80	ns
TRise01	Rise Time, Strong Mode, Cload = 50 pF Ports 0 or 1	Vdd = 3.0 to 3.6V, 10% – 90% LDO enabled or disabled	10	–	50	ns
TRise01L	Rise Time, Strong Mode Low Supply, Cload = 50 pF, Ports 0 or 1	Vdd = 1.71 to 3.0V, 10% – 90% LDO enabled or disabled	10	–	80	ns
TFall	Fall Time, Strong Mode, Cload = 50 pF All Ports	Vdd = 3.0 to 3.6V, 10% – 90%	10	–	50	ns
TFallL	Fall Time, Strong Mode Low Supply, Cload = 50 pF, All Ports	Vdd = 1.71 to 3.0V, 10% – 90%	10	–	70	ns

Figure 12. GPIO Timing Diagram

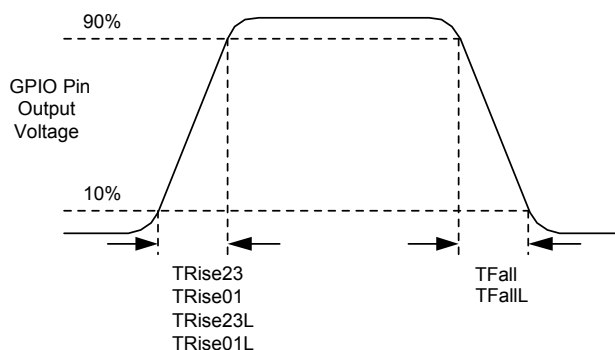


Table 27.AC Characteristics – USB Data Timings

Symbol	Description	Conditions	Min	Typ	Max	Units
Td _{rate}	Full speed data rate	Average bit rate	12–0.25%	12	12 + 0.25%	MHz
Td _{j1}	Receiver data jitter tolerance	To next transition	-18.5	–	18.5	ns
Td _{j2}	Receiver data jitter tolerance	To pair transition	-9	–	9	ns
Tu _{d1}	Driver differential jitter	To next transition	-3.5	–	3.5	ns
Tu _{d2}	Driver differential jitter	To pair transition	-4.0	–	4.0	ns
Tf _{deop}	Source jitter for differential transition	To SE0 transition	-2	–	5	ns
Tf _{eopt}	Source SE0 interval of EOP		160	–	175	ns
Tf _{eopr}	Receiver SE0 interval of EOP		82	–		ns
Tf _{st}	Width of SE0 interval during differential transition			–	14	ns

Table 28.AC Characteristics – USB Driver

Symbol	Description	Conditions	Min	Typ	Max	Units
Tr	Transition rise time	50 pF	4	–	20	ns
Tf	Transition fall time	50 pF	4	–	20	ns
TR	Rise/fall time matching		90.00	–	111.1	%
V _{crs}	Output signal crossover voltage		1.3	–	2.0	V

AC Comparator Specifications

The following table lists guaranteed maximum and minimum specifications for the entire voltage and temperature ranges.

Table 29. AC Low Power Comparator Specifications

Symbol	Description	Conditions	Min	Typ	Max	Units
T _{LPC}	Comparator Response Time, 50 mV Overdrive	50 mV overdrive does not include offset voltage.			100	ns

AC Analog Mux Bus Specifications

The following table lists guaranteed maximum and minimum specifications for the entire voltage and temperature ranges.

Table 30. AC Analog Mux Bus Specifications

Symbol	Description	Conditions	Min	Typ	Max	Units
F _{SW}	Switch Rate	Maximum pin voltage when measuring switch rate is 1.8Vp-p	–	–	6.3	MHz

AC External Clock Specifications

The following table lists guaranteed maximum and minimum specifications for the entire voltage and temperature ranges.

Table 31. AC External Clock Specifications

Symbol	Description	Conditions	Min	Typ	Max	Units
F _{OSCEXT}	Frequency		0.750	–	25.2	MHz
–	High Period		20.6	–	5300	ns
–	Low Period		20.6	–	–	ns
–	Power Up IMO to Switch		150	–	–	μs

Table 34. SPI Master AC Specifications

Symbol	Description	Conditions	Min	Typ	Max	Units
F_{SCLK}	SCLK clock frequency	$V_{DD} \geq 2.4V$ $V_{DD} < 2.4V$			6 3	MHz
DC	SCLK duty cycle			50		%
T_{SETUP}	MISO to SCLK setup time	$V_{DD} \geq 2.4V$ $V_{DD} < 2.4V$	60 100			ns
T_{HOLD}	SCLK to MISO hold time		40			ns
T_{OUT_VAL}	SCLK to MOSI valid time				40	ns
T_{OUT_HIGH}	MOSI high time		40			ns

Table 35. SPI Slave AC Specifications

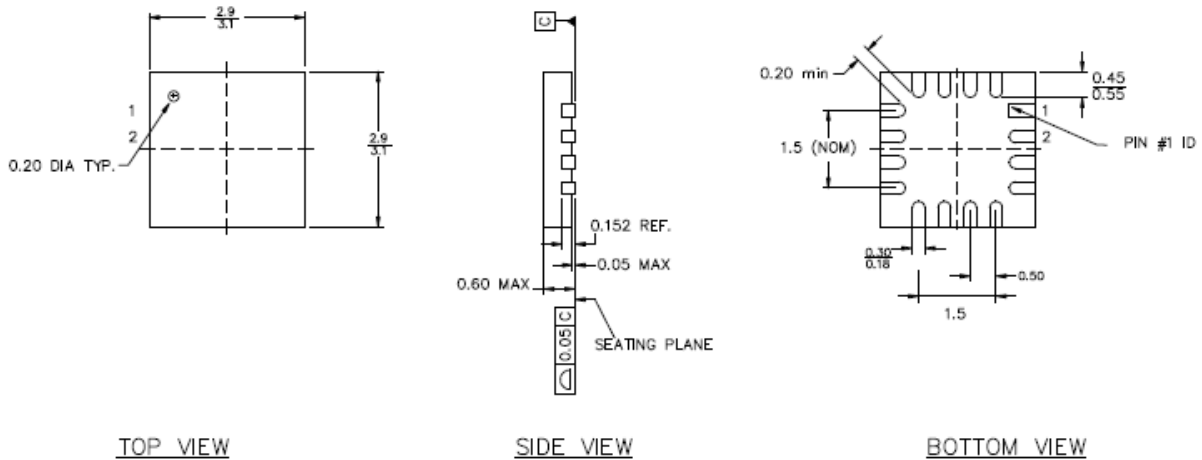
Symbol	Description	Conditions	Min	Typ	Max	Units
F_{SCLK}	SCLK clock frequency	$V_{DD} \geq 2.4V$ $V_{DD} < 2.4V$			12 6	MHz
T_{LOW}	SCLK low time		41.67			ns
T_{HIGH}	SCLK high time		41.67			ns
T_{SETUP}	MOSI to SCLK setup time		30			ns
T_{HOLD}	SCLK to MOSI hold time		50			ns
T_{SS_MISO}	SS high to MISO valid				153	ns
T_{SCLK_MISO}	SCLK to MISO valid				125	ns
T_{SS_HIGH}	SS high time				50	ns
T_{SS_CLK}	Time from SS low to first SCLK		2/SCLK			ns
T_{CLK_SS}	Time from last SCLK to SS high		2/SCLK			ns

Packaging Information

This section illustrates the packaging specifications for the CY8C20x36/46/66/96 PSoC device, along with the thermal impedances for each package.

Important Note Emulation tools may require a larger area on the target PCB than the chip's footprint. For a detailed description of the emulation tools' dimensions, refer to the document titled *PSoC Emulator Pod Dimensions* at <http://www.cypress.com/design/MR10161>.

Figure 15. 16-pin QFN No E-pad 3x3mm Package Outline (Sawn)



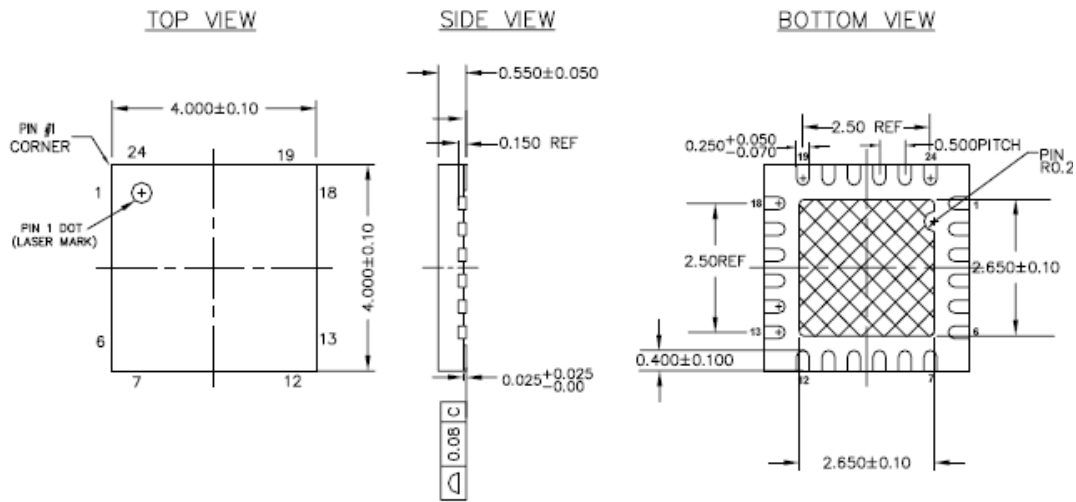
PART NO.	DESCRIPTION
LG16A	LEAD-FREE
LD16A	STANDARD

NOTES:


1. JEDEC # MD-220
2. Package Weight: 0.014g
3. DIMENSIONS IN MM, MIN
MAX

001-09116 *D

Figure 16. 24-Pin (4x4 x 0.6 mm) QFN

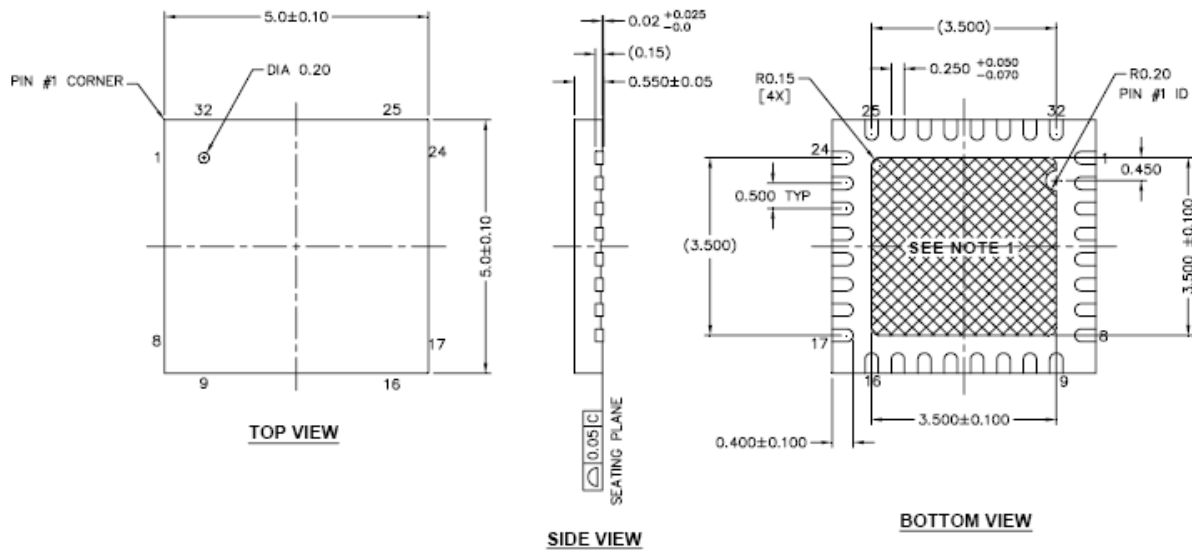


NOTES :


1.  HATCH IS SOLDERABLE EXPOSED METAL.
2. REFERENCE JEDEC # MO-248
3. UNIT PACKAGE WEIGHT : 0.024 grams
4. ALL DIMENSIONS ARE IN MILLIMETERS

001-13937 *B

Figure 17. 32-Pin (5x5 x 0.6 mm) QFN



NOTES:

1.  HATCH AREA IS SOLDERABLE EXPOSED PAD
2. BASED ON REF JEDEC # MO-248
3. PACKAGE WEIGHT: 0.0388g
4. DIMENSIONS ARE IN MILLIMETERS

001-42168 °C

Figure 18. 48-Pin (300 MIL) SSOP

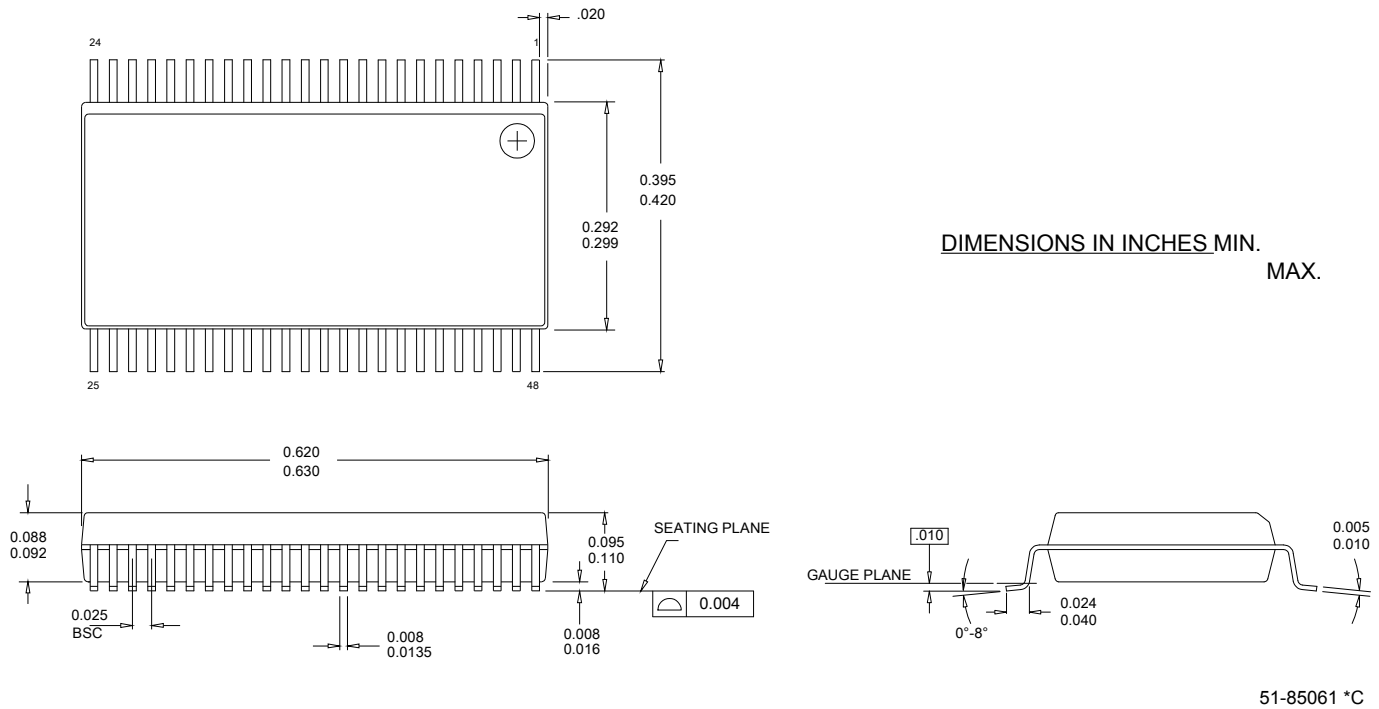
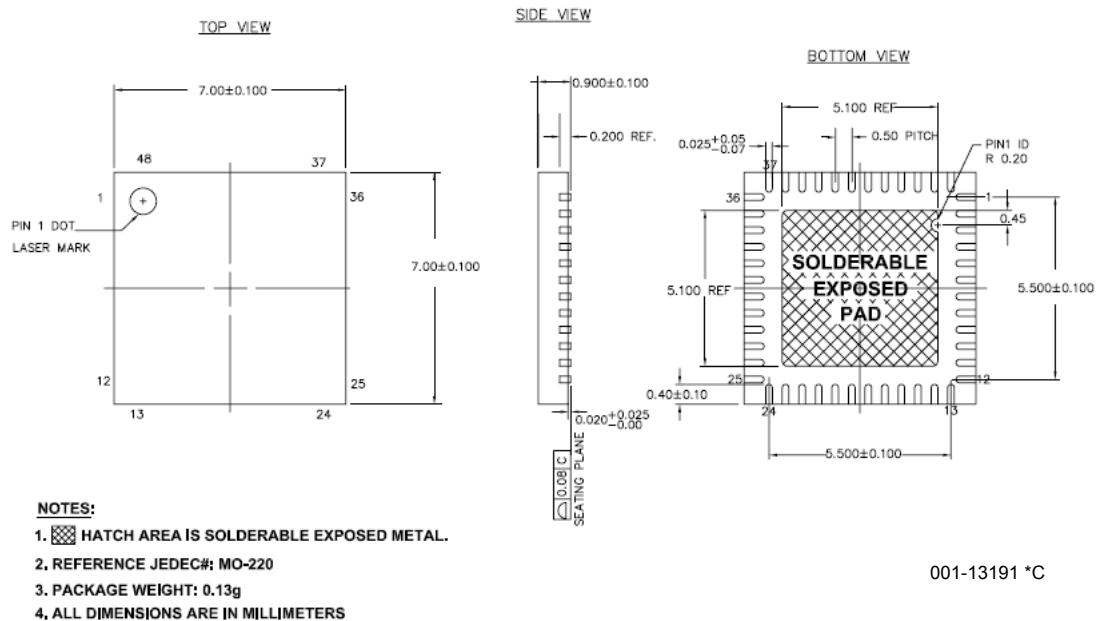


Figure 19. 48-Pin (7x7 mm) QFN



Important Notes

- For information on the preferred dimensions for mounting QFN packages, see the following Application Note at http://www.amkor.com/products/notes_papers/MLFAppNote.pdf.
- Pinned vias for thermal conduction are not required for the low power PSoC device.

Device Programmers

All device programmers are purchased from the Cypress Online Store.

CY3216 Modular Programmer

The CY3216 Modular Programmer kit features a modular programmer and the MiniProg1 programming unit. The modular programmer includes three programming module cards and supports multiple Cypress products. The kit includes:

- Modular Programmer Base
- Three Programming Module Cards
- MiniProg Programming Unit
- PSoC Designer Software CD
- Getting Started Guide
- USB 2.0 Cable

CY3207ISSP In-System Serial Programmer (ISSP)

The CY3207ISSP is a production programmer. It includes protection circuitry and an industrial case that is more robust than the MiniProg in a production programming environment.

Note that CY3207ISSP needs special software and is not compatible with PSoC Programmer. The kit includes:

- CY3207 Programmer Unit
- PSoC ISSP Software CD
- 110 ~ 240V Power Supply, Euro-Plug Adapter
- USB 2.0 Cable

Accessories (Emulation and Programming)

Table 38. Emulation and Programming Accessories

Part Number	Pin Package	Flex-Pod Kit ^[15]	Foot Kit ^[16]	Adapter ^[17]
CY8C20236-24LKXI	16 QFN	CY3250-20266QFN	CY3250-16QFN-RK	See note 15
CY8C20246-24LKXI	16 QFN	CY3250-20266QFN	CY3250-16QFN-FK	See note 17
CY8C20336-24LQXI	24 QFN	CY3250-20366QFN	CY3250-24QFN-FK	See note 15
CY8C20346-24LQXI	24 QFN	CY3250-20366QFN	CY3250-24QFN-FK	See note 17
CY8C20396-24LQXI	24 QFN	Not Available		
CY8C20436-24LQXI	32 QFN	CY3250-20466QFN	CY3250-32QFN-RK	See note 15
CY8C20446-24LQXI	32 QFN	CY3250-20466QFN	CY3250-32QFN-FK	See note 17
CY8C20466-24LQXI	32 QFN	CY3250-20466QFN	CY3250-32QFN-FK	See note 17
CY8C20496-24LQXI	32 QFN	Not Available		
CY8C20536-24PVXI	48 SSOP	CY3250-20X66	CY3250-48SSOP-FK	See note 17
CY8C20546-24PVXI	48 SSOP	CY3250-20X66	CY3250-48SSOP-FK	See note 17
CY8C20566-24PVXI	48 SSOP	CY3250-20X66	CY3250-48SSOP-FK	See note 17
CY8C20636-24LTXI	48 QFN	CY3250-20666QFN	CY3250-48QFN-FK	See note 17
CY8C20646-24LTXI	48 QFN	CY3250-20666QFN	CY3250-48QFN-FK	See note 17
CY8C20666-24LTXI	48 QFN	CY3250-20666QFN	CY3250-48QFN-FK	See note 17

Third-Party Tools

Several tools have been specially designed by the following third-party vendors to accompany PSoC devices during development and production. Specific details for each of these tools can be found at <http://www.cypress.com> under Documentation > Evaluation Boards.

Build a PSoC Emulator into Your Board

For details on how to emulate your circuit before going to volume production using an on-chip debug (OCD) non-production PSoC device, refer Application Note "Debugging - Build a PSoC Emulator into Your Board - AN2323" at <http://www.cypress.com/?rID2748>.

Notes

15. Flex-Pod kit includes a practice flex-pod and a practice PCB, in addition to two flex-pods.

16. Foot kit includes surface mount feet that can be soldered to the target PCB.

17. Programming adapter converts non-DIP package to DIP footprint. Specific details and ordering information for each of the adapters can be found at <http://www.emulation.com>.

Ordering Information

The following table lists the CY8C20x36/46/66/96 PSoC devices' key package features and ordering codes.

Table 39. PSoC Device Key Features and Ordering Information

Package	Ordering Code	Flash (Bytes)	SRAM (Bytes)	CapSense Blocks	Digital I/O Pins	Analog Inputs ^[18]	XRES Pin	USB
16-Pin (3x3x0.6mm) QFN	CY8C20236-24LKXI	8K	1K	1	13	13	Yes	No
16-Pin (3x3x0.6mm) QFN (Tape and Reel)	CY8C20236-24LKXIT	8K	1K	1	13	13	Yes	No
16 Pin (3x3 x 0.6 mm) QFN	CY8C20246-24LKXI	16K	2K	1	13	13	Yes	No
16 Pin (3x3 x 0.6 mm) QFN (Tape and Reel)	CY8C20246-24LKXIT	16K	2K	1	13	13	Yes	No
24-Pin (4x4x0.6mm) QFN	CY8C20336-24LQXI	8K	1K	1	20	20	Yes	No
24-Pin (4x4x0.6mm) QFN (Tape and Reel)	CY8C20336-24LQXIT	8K	1K	1	20	20	Yes	No
24 Pin (4x4 x 0.6 mm) QFN	CY8C20346-24LQXI	16K	2K	1	20	20	Yes	No
24 Pin (4x4 x 0.6 mm) QFN (Tape and Reel)	CY8C20346-24LQXIT	16K	2K	1	20	20	Yes	No
24-Pin (4x4x0.6mm) QFN	CY8C20396-24LQXI	16K	2K	1	19	19	Yes	Yes
24-Pin (4x4x0.6mm) QFN (Tape and Reel)	CY8C20396-24LQXIT	16K	2K	1	19	19	Yes	Yes
32-Pin (5x5x0.6mm) QFN	CY8C20436-24LQXI	8K	1K	1	28	28	Yes	No
32-Pin (5x5x0.6mm) QFN (Tape and Reel)	CY8C20436-24LQXIT	8K	1K	1	28	28	Yes	No
32 Pin (5x5 x 0.6 mm) QFN	CY8C20446-24LQXI	16K	2K	1	28	28	Yes	No
32 Pin (5x5 x 0.6 mm) QFN (Tape and Reel)	CY8C20446-24LQXIT	16K	2K	1	28	28	Yes	No
32 Pin (5x5 x 0.6 mm) QFN	CY8C20466-24LQXI	32K	2K	1	28	28	Yes	No
32 Pin (5x5 x 0.6 mm) QFN (Tape and Reel)	CY8C20466-24LQXIT	32K	2K	1	28	28	Yes	No
32 Pin (5x5 x 0.6 mm) QFN	CY8C20496-24LQXI	16K	2K	1	25	25	Yes	No
32 Pin (5x5 x 0.6 mm) QFN (Tape and Reel)	CY8C20496-24LQXIT	16K	2K	1	25	25	Yes	No
48-Pin SSOP	CY8C20536-24PVXI	8K	1K	1	36	36	Yes	No
48-Pin SSOP (Tape and Reel)	CY8C20536-24PVXIT	8K	1K	1	36	36	Yes	No
48-Pin SSOP	CY8C20546-24PVXI	16K	2K	1	36	36	Yes	No
48-Pin SSOP (Tape and Reel)	CY8C20546-24PVXIT	16K	2K	1	36	36	Yes	No
48-Pin SSOP	CY8C20566-24PVXI	32K	2K	1	36	36	Yes	No
48-Pin SSOP (Tape and Reel)	CY8C20566-24PVXIT	32K	2K	1	36	36	Yes	No
48 Pin (7x7 mm) QFN	CY8C20636-24LTXI	8K	1K	1	36	36	Yes	No
48 Pin (7x7 mm) QFN (Tape and Reel)	CY8C20636-24LTXIT	8K	1K	1	36	36	Yes	No
48 Pin (7x7 mm) QFN	CY8C20646-24LTXI	16K	2K	1	36	36	Yes	Yes
48 Pin (7x7 mm) QFN (Tape and Reel)	CY8C20646-24LTXIT	16K	2K	1	36	36	Yes	Yes
48 Pin (7x7 mm) QFN	CY8C20666-24LTXI	32K	2K	1	36	36	Yes	Yes
48 Pin (7x7 mm) QFN (Tape and Reel)	CY8C20666-24LTXIT	32K	2K	1	36	36	Yes	Yes
48 Pin (7x7 mm) QFN (OCD) ^[4]	CY8C20066-24LTXI	32K	2K	1	36	36	Yes	Yes

Notes

18. Dual-function Digital I/O Pins also connect to the common analog mux.

Document History Page

Document Title: CY8C20x36/46/66/96 CapSense® Applications Document Number: 001-12696				
Revision	ECN	Origin of Change	Submission Date	Description of Change
**	766857	HMT	See ECN	New silicon and document (Revision **).
*A	1242866	HMT	See ECN	Add features. Update all applicable sections. Update specs. Fix 24-pin QFN pinout moving pins inside. Update package revisions. Update and add to Emulation and Programming Accessories table.
*B	2174006	AESA	See ECN	Added 48-Pin SSOP Part Pinout Modified symbol R_{VDD} to R_{GND} in Table DC Analog Mux Bus Specification Added footnote in Table DC Analog Mux Bus Specification Added 16K FLASH Parts. Updated Notes, Package Diagrams and Ordering Information table. Updated Thermal Impedance and Solder Reflow tables
*C	2587518	TOF/JASM/MNU/ HMT	10/13/08	Converted from Preliminary to Final Fixed broken links. Updated data sheet template. Added operating voltage ranges with USB ADC resolution changed from 10-bit to 8-bit Included ADC specifications table Included Comparator specification table Included Voh7, Voh8, Voh9, Voh10 specs Flash data retention – condition added to Note Input leakage spec changed to 1 μ A max GPIO rise time for ports 0,1 and ports 2,3 made common AC Programming specifications updated Included AC Programming cycle timing diagram AC SPI specification updated The VIH for $3.0 < V_{dd} < 2.4$ changed to 1.6 from 2.0 Added USB specification Added SPI CLK to P1[0] Updated package diagrams Updated thermal impedances for QFN packages Updated F_{GPIO} parameter in Table 23 Updated voltage ranges for F_{SPIM} and F_{SPIS} in Table 30 Update Development Tools, add Designing with PSoC Designer. Edit, fix links, notes and table format. Update R_{IN} formula, fix TRise parameter names in GPIO figure, fix Switch Rate note. Update maximum data in Table 20. DC POR and LVD Specifications.
*D	2649637	SNV/AESA	03/17/2009	Changed title to “CY8C20x36/46/66, CY8C20396 CapSense™ Applications”. Updated data sheet Features, pin information, and ordering information sections. Updated package diagram 001-42168 to *C.
*E	2700196	SNV/PYRS	04/30/2009	Added part numbers CY8C20496, CY8C20536, CY8C20546, CY8C20636, CY8C20646 Updated Features on page 1 Added 48-Pin QFN without USB pin Diagram and Pin Definition table Added 32-Pin QFN (with USB) package Added SPI Master and Slave AC Specifications Updated Emulations and Programming Accessories Table on page 33 Updated Ordering Information on page 37 Removed reference to Hi-Tech C Compiler in Development Tool Selection on page 35